



Material Content Data Sheet



Sales Product Name		IPB100N10S3-05		Issued		29. August 2013		
MA#		MA000389808						
Package		PG-TO263-3-2		Weight*		1469.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.224	1.04	1.04	10363	10363
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	57.96	58.04	579769	580524
wire	non noble metal	aluminium	7429-90-5	8.441	0.57	0.57	5746	5746
encapsulation	organic material	carbon black	1333-86-4	8.625	0.59		5871	
	plastics	epoxy resin	-	94.872	6.46		64581	
	inorganic material	silicondioxide	60676-86-0	471.483	32.10	39.15	320950	391402
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6574	6574
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	non noble metal	tin	7440-31-5	0.154	0.01		105	
	noble metal	silver	7440-22-4	0.192	0.01		131	
	non noble metal	lead	7439-92-1	7.344	0.50	0.52	4999	5235
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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